

HKN TechX is IEEE-HKN's premier technical and networking event, bringing together IEEE Technical Societies and industry leaders to inspire students and young engineers by focusing on emerging technologies and their applications. This is your invitation to be a thought leader as we address the technical challenges engineers need to be prepared to meet.

Leverage the power of our interactive, one-stop event platform to get the most out of your sponsorship. Our online experience features a reception area, an event stage, custom booths in the Expo Hall for technical conversations and small-group networking; attendee profiles, interactive networking, and embedded chat and video calls. It is mobile-friendly, and you can schedule meetings and interviews without having to leave the platform. You will receive conference analytics and tickets to attend all sessions.

Sponsors can speak at sessions, be panelists or both. All sessions will be made available for on-demand viewing, which multiplies viewership and clicks. Custom packages are available.

A **Recruitment Fair**, to be held in conjunction with the conference, gives employers and graduate schools the opportunity to schedule appointments directly with students and early career professionals. All packages include our Resume Book for all attendees.

Secure your booth for this event now.

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I have been receiving the daily events that IEEE-HKN runs. It is most impressive, and I compliment you and your team on putting together so much content and programming."

LEONARD KLEINROCK A Father of the Internet and HKN Eminent Member







IEEE-Eta Kappa Nu HKN TechX Experience PACKAGES and RATES

PLATINUM 3 Available	GOLD 4 Available	SILVER 4 Available
\$5,000	\$2,500	\$1,500
Exclusive to this level:	Exclusive to this level:	Exclusive to this level:
 A keynote address and social media promotion 	Sponsor of a 1-hour learning session or of a 1-hour small-	Panelist on one session4 conference tickets
Choice of HKN Connection or Career Conversation Podcast	group networking session • 1/4 page ad in <i>THE BRIDGE</i>	• Listing in <i>THE BRIDGE</i>
8 registrations	6 conference tickets	
■ 1/2 page ad in THE BRIDGE		

Gold and Silver Sponsor Packages Include:

- A fully customizable booth (add company profile, logo, photos, video, etc.) in the Expo Hall and Recruitment Fair
 for full conference
 - The opportunity to host small-group sessions and one-on-one conversations with attendees
 - The ability to set your own live booth hours plus use your booth to have your experts lead interactive discussions on emerging technologies
 - An electronic, indexed Resume Book with resumes and CVs from all attendees who opt to share their data
- Clickable logo on the conference website
- 5 conference-specific newsletters sent via direct email campaign
- Exclusive social media post for your company on LinkedIn, Facebook, Instagram, and X
- Add-on conference tickets at an additional cost
- Access conference analytics
- Gain access to recorded content beyond the conference
- Conference Ticket holders can:
 - Create customized profiles on the conference platform. Profile can include video, photos, clickable links to job postings, and contact information
 - Chat, video chat, and schedule meetings with conference attendees.
 - Invite candidates to your own interview room
 - Access all learning and networking sessions

Recruitment Fair Only

\$800

- A fully customized booth (show company profile video, add photos, link to job postings) in the Expo Hall and Recruitment Fair for full conference with 2 seats
- An electronic, indexed Resume Book with resumes and CVs from all attendees who opt to share their data
- Schedule and hold meetings/interviews during dedicated **Recruitment Fair** hours with conference attendees with live video chat integrations
- Add-on conference tickets at an additional cost
- Social Media posts prior to and during event

Contact us to customize a package that meets your goals. Single- and multi-event sponsorships, and digital advertising opportunities are available. Contact Nancy Ostin at n.ostin@ieee.org